

Haegyung Jang

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Characterization of Low Temperature Graphene Synthesis in Inductively Coupled Plasma Chemical Vapor Deposition Process with Optical Emission Spectroscopy. Journal of Nanoscience and Nanotechnology, 2014, 14, 9065-9072.	0.9	13
2	Sensitivity Enhancement of Dielectric Plasma Etching Endpoint Detection by Optical Emission Spectra With Modified K-Means Cluster Analysis. IEEE Transactions on Semiconductor Manufacturing, 2017, 30, 17-22.	1.7	13
3	Real-Time Endpoint Detection of Small Exposed Area SiO ₂ Films in Plasma Etching Using Plasma Impedance Monitoring with Modified Principal Component Analysis. Plasma Processes and Polymers, 2013, 10, 850-856.	3.0	10
4	Sensitivity Enhancement of SiO ₂ Plasma Etching Endpoint Detection Using Modified Gaussian Mixture Model. IEEE Transactions on Semiconductor Manufacturing, 2020, 33, 252-257.	1.7	10
5	Non-Invasive Plasma Monitoring Tools and Multivariate Analysis Techniques for Sensitivity Improvement. Applied Science and Convergence Technology, 2014, 23, 328-339.	0.9	4
6	Effect of Dual Radio Frequency Bias Power on SiO ₂ Sputter Etching in Inductively Coupled Plasma. Nano, 2017, 12, 1750025.	1.0	3
7	Characterization of Low-k Dielectric SiCOH Films Deposited with Decamethylcyclopentasiloxane and Cyclohexane. Journal of Nanoscience and Nanotechnology, 2012, 12, 6040-6044.	0.9	2
8	Characterization of Low-k SiCOH Film Etching in Fluorocarbon Inductively Coupled Plasmas. Nanoscience and Nanotechnology Letters, 2017, 9, 174-178.	0.4	2
9	Patterning of Si ₃ N ₄ Layer in Pulse-Biased Capacitively-Coupled Plasmas for Multi-Level Hard Mask Structures. Journal of Nanoscience and Nanotechnology, 2016, 16, 11817-11822.	0.9	1